

**BRAND NEW SUPPLEMENT  
FOR SMARTER  
INJECTION MOLDING!**

Application Software for  
Low Pressure Injection Molding  
for Electric Machines

**K-SAPLI**



K-SAPLI will reduce your workload in your molding factory.



**SAPLI Series** is the application software for low-pressure injection molding. It helps you improve the production yield and reduce mold maintenance workload and general running costs.

**What is SAPLI Series?** ✓ Supplement for smart injection molding  
✓ Smart Applications for **PL**astic Injection

【Effect of SAPLI】 = Reason for High Performance

➤ **Reduction of Molding Defects**

Removal of flash, warpage, sink mark, burning, and short shot. Induce gas venting.

➤ **Reduction in Cycle Time**

Reduction in injection (Holding pressure) time, cooling time

➤ **Improvement in Productivity and Molding Quality**

Simple molding condition

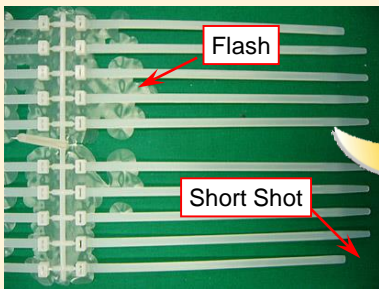
➤ **Long-Lasting Use of Mold**

Reduction in mold maintenance costs

Example of K-SAPLI Molding

**Removal of Flash & Short Shot**

Product: Tying band (20pcs per shot)  
Resin: PP



Mix of flash & short shot ⇒  
No solution before



Apply K-SAPLI

**Reduce clamping force**  
**Do not forcibly fill-up**  
**Reduce injection velocity**  
No defects with above factors.

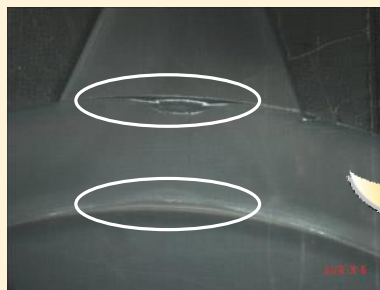
**Removal of Defects & Reduction of Workload with 0 ton Clamping Force**

Comparison of Molding with Testing Mold for Mold Deposit (without gas vent)



Gate

There is a case of continual operation of up to 270,000 shots by K-SAPLI, though it needed mold maintenance once in 40,000 shots.



▲ Clamping Force: 15t

Gas remained at the end of molding product. Photo below shows insufficient molding of the edge.



▲ Clamping Force: 0t

★ Remove insufficient gas venting



▲ Clamping Force: 15t

Deposit on mold surface.



▲ Clamping Force: 0t

★ Reduce mold maintenance workload

\*The software can only be installed in TACT controller of Nissei Plastic Industrial Co., Ltd.  
\* It is not guaranteed that SAPLI series is compatible with any molds and resin materials.  
\* Specification of SAPLI series is subject to change without prior notice.